

Insulation Materials

Product Information Sheet

Product

GAP PAD® VIA00

Product Description

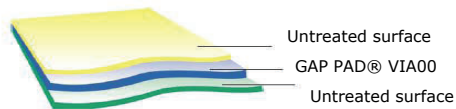
GAP PAD® VIA00 is a thermal conductive interface material designed to fill gaps between hot devices and their heat spreaders.

Available in 0.508mm – 5.08mm.

Key Features

- Low-stress vibration dampening
- Electrically isolating
- Enhanced puncture, shear and tear resistance

Structure of GAP PAD® VIA00



Property	Test Method	Unit	Value
Colour	Visual	-	Mauve/Pink
Reinforcement carrier	-	-	Sil-pad
Inherent surface tack (1 or 2 sided)	-	-	1
Density	ASTM D792	g/cc	1.6
Dielectric breakdown voltage	ASTM D149	Vac	>6000
Dielectric constant	ASTM D150	1000Hz	5.5
Volume resistance	ASTM D257	Ohm meter	10 ¹¹
Flame rating	UL94	-	V-0
Thermal conductivity	ASTM D5470	W/m-K	0.8

Applications

GAP PAD® VIA00 used where a minimum amount of pressure on components is required. Extensively used in the telecommunications industry. Computer and peripherals

The information above is given in good faith and should be considered as a guide not a specification.



BS EN 14644 : 1999
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